IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Darbha et al.

Art Unit:

Serial No.:

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Filed:

Examiner:

Title: STRESS REDUCTION IN FLIP-CHIP PBGA PACKAGING BY UTILIZING SEGMENTED CHIPS AND/OR CHIP CARRIERS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination